

03-05-2007



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To the Director of the U.S. Patent

103377529

and documents or the new address(es) below. **FINANCE SECTION**

1. Name of conveying party(ies)

Ting Chieh Su
Chin Chang Liao
Jun Cheng Huang

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) 01/25/07; 11/01/06; and
11/01/06 respectively

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other _____

2. Name and address of receiving party(ies)

Semiconductor Manufacturing

Name: International (Shanghai) Corporation

Internal Address: _____

Street Address: 18 Zhang Jiang Rd.,
Pudong New Area

City: Shanghai

State: _____

Country: People's Republic of China Zip: 201203

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

A. Patent Application No.(s)
11/517,546

☐ This document is being filed together with a new application.
B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Richard T. Ogawa

Internal Address: _____

TOWNSEND AND TOWNSEND AND CREW LLP

Street Address: Two Embarcadero Center,
Eighth Floor

City: San Francisco

State: California Zip: 94111-3834

Phone Number: (415) 576-0200

Fax Number: (415) 576-0300

Email Address: RTOgawa@townsend.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☐ Authorized to be charged by credit card
☒ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 numbers _____
Expiration Date _____

b. Deposit Account Number 20-1430

Authorized User Name Townsend and

Townsend and Crew LLP

9. Signature:

Signature
Richard T. Ogawa

February 26, 2007

Date

Name of Person Signing Atty. Reg. No. 37,692

Total number of pages including cover sheet, attachments, and documents: 8

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, **Ting Chieh Su** of No. 61, Guang Ming 5th Rd., Nantou, Republic of China; **Min Chie Jeng** of 10577 Johansen Drive, Cupertino, CA 95014; **Chin Chang Liao** of 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China; and **Jun Cheng Huang** of 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: **SYSTEM AND METHOD FOR I/O ESD PROTECTION
WITH FLOATING AND/OR BIASED POLYSILICON
REGIONS**

Filing Date: **September 6, 2006**

Application No.: **11/517,546; and**

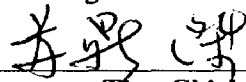
WHEREAS, **Semiconductor Manufacturing International (Shanghai) Corporation**, a corporation of People's Republic of China, located at 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: 1/25, 2007


Ting Chieh Su

Dated: _____

Min Chie Jeng

Dated: _____

Chin Chang Liao

Dated: _____

Jun Cheng Huang

Attorney Docket No.: 021653-014700US

Client Reference No.: I-04-229

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JOINT

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IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: _____

Ting Chieh Su

Dated: _____

Min Chie Jeng

Dated: 2006/11/11

Chin Chang Liao

Dated: 2006/11/11

Jun Cheng Huang
PATENT